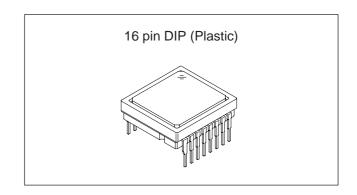
ICX059CK

Diagonal 6mm (Type 1/3) CCD Image Sensor for PAL Color Video Camera

Description

The ICX059CK is an interline CCD solid-state image sensor suitable for PAL color video cameras. Compared with the current product ICX059AK, sensitivity is improved drastically through the adoption of Super HAD CCD technology. High resolution is achieved through the use of Ye, Cy, Mg, and G complementary color mosaic filters.

This chip features a field period readout system and an electronic shutter with variable charge-storage time.



Features

- High sensitivity (+3dB at F5.6, +4dB at F1.2 compared with ICX059AK)
- High resolution, low smear and low dark current
- · Excellent antiblooming characteristics
- · Continuous variable-speed shutter
- Ye, Cy, Mg, and G complementary color mosaic filters on chip

Horizontal register: 5V drive Reset gate: 5V drive

Pin 1 2 V | 12 3 | H | 40

Optical black position (Top View)

Device Structure

Interline CCD image sensor

• Image size: Diagonal 6mm (Type 1/3)

Number of effective pixels: 752 (H) × 582 (V) approx. 440K pixels
 Number of total pixels: 795 (H) × 596 (V) approx. 470K pixels

 $\begin{array}{ll} \bullet \; \text{Chip size:} & 6.00\text{mm (H)} \times 4.96\text{mm (V)} \\ \bullet \; \text{Unit cell size:} & 6.50\mu\text{m (H)} \times 6.25\mu\text{m (V)} \\ \end{array}$

Optical black: Horizontal (H) direction: Front 3 pixels, rear 40 pixels

Vertical (V) direction: Front 12 pixels, rear 2 pixels

• Number of dummy bits: Horizontal 22

Vertical 1 (even field only)

Substrate material: Silicon

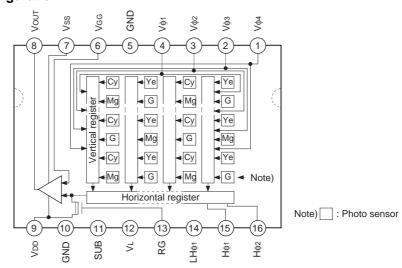
Super HAD CCD®

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^{*}Super HAD CCD is a registered trademark of Sony Corporation. Super HAD CCD is a CCD that drastically improves sensitivity by introducing newly developed semiconductor technology by Sony Corporation into Sony's high-performance HAD (Hole-Accumulation Diode) sensor.

Block Diagram and Pin Configuration

(Top View)



Pin Description

| Pin No. | Symbol | Description | Pin No. | Symbol | Description |
|---------|--------|----------------------------------|---------|------------------|--|
| 1 | Vф4 | Vertical register transfer clock | 9 | Vdd | Output amplifier drain supply |
| 2 | Vфз | Vertical register transfer clock | 10 | GND | GND |
| 3 | Vф2 | Vertical register transfer clock | 11 | SUB | Substrate (Overflow drain) |
| 4 | Vф1 | Vertical register transfer clock | 12 | VL | Protective transistor bias |
| 5 | GND | GND | 13 | RG | Reset gate clock |
| 6 | Vgg | Output amplifier gate bias | 14 | LH _{φ1} | Horizontal register final stage transfer clock |
| 7 | Vss | Output amplifier source | 15 | Нф1 | Horizontal register transfer clock |
| 8 | Vouт | Signal output | 16 | Нф2 | Horizontal register transfer clock |

Absolute Maximum Ratings

| | Item | Ratings | Unit | Remarks |
|------------------------------|-------------------------------|-------------|------|---------|
| Substrate voltage SUB – 0 | GND | -0.3 to +55 | V | |
| Cupply voltage | Vdd, Vout, Vss – GND | -0.3 to +18 | V | |
| Supply voltage | VDD, VOUT, VSS – SUB | −55 to +10 | V | |
| Vertical clock input voltage | Vφ1, Vφ2, Vφ3, Vφ4 – GND | −15 to +20 | V | |
| vertical clock input voltage | Vφ1, Vφ2, Vφ3, Vφ4 – SUB | to +10 | V | |
| Voltage difference betwee | n vertical clock input pins | to +15 | V | *1 |
| Voltage difference betwee | n horizontal clock input pins | to +17 | V | |
| Hφ1, Hφ2 – Vφ4 | | −17 to +17 | V | |
| Ηφ1, Ηφ2, LΗφ1, RG, Vgg- | · GND | −10 to +15 | V | |
| Ηφ1, Ηφ2, LΗφ1, RG, Vgg- | SUB | −55 to +10 | V | |
| VL-SUB | | -65 to +0.3 | V | |
| Vφ1, Vφ2, Vφ3, Vφ4, VDD, V0 | DUT — VL | -0.3 to +30 | V | |
| RG – VL | | -0.3 to +24 | V | |
| Vgg, Vss, Hφ1, Hφ2, LHφ1 - | - VL | -0.3 to +20 | V | |
| Storage temperature | | -30 to +80 | °C | |
| Operating temperature | | -10 to +60 | °C | |

^{*1 +27}V (Max.) when clock width < 10µs, clock duty factor < 0.1%.

Bias Conditions

| Item | Symbol | Min. | Тур. | Max. | Unit | Remarks |
|---|----------------|-------|-----------------------|-------|------|---------|
| Output amplifier drain voltage | VDD | 14.55 | 15.0 | 15.45 | V | |
| Output amplifier gate voltage | Vgg | 3.8 | 4.2 | 4.65 | V | |
| Output amplifier source | Vss | | ounded w 20Ω resis | | | ±5% |
| Substrate voltage adjustment range | VsuB | 9.0 | | 18.5 | V | *1 |
| Fluctuation range after substrate voltage adjustment | ΔVsub | -3 | | +3 | % | |
| Reset gate clock voltage adjustment range | VRGL | 1.0 | | 4.0 | V | *1, *6 |
| Fluctuation range after reset gate clock voltage adjustment | ΔV RGL | -3 | | +3 | % | |
| Protective transistor bias | VL | | *2 | | | |

DC Characteristics

| Item | Symbol | Min. | Тур. | Max. | Unit | Remarks |
|--------------------------------|------------------|------|------|------|------|---------|
| Output amplifier drain current | IDD | | 5 | | mA | |
| Input current | lin1 | | | 1 | μA | *3 |
| Input current | l _{IN2} | | | 10 | μA | *4 |

^{*1} Indications of substrate voltage (Vsub) · reset gate clock voltage (Vrgl) setting value.

The setting values of substrate voltage and reset gate clock voltage are indicated on the back of the image sensor by a special code. Adjust substrate voltage (Vsub) and reset gate clock voltage (VRGL) to the indicated voltage. Fluctuation range after adjustment is ±3%.

VsuB code one character indication □ □ □
VRGL code one character indication ↑ ↑

VRGL code VSUB code

Code and optimal setting correspond to each other as follows.

| Vrgl code | 1 | 2 | 3 | 4 | 5 | 6 | 7 |
|-----------------|-----|-----|-----|-----|-----|-----|-----|
| Optimal setting | 1.0 | 1.5 | 2.0 | 2.5 | 3.0 | 3.5 | 4.0 |

| VsuB code | Е | f | G | h | J | K | L | m | Ν | Р | Q | R | S | Т | U | V | W | Х | Υ | Z |
|-----------------|-----|-----|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|
| Optimal setting | 9.0 | 9.5 | 10.0 | 10.5 | 11.0 | 11.5 | 12.0 | 12.5 | 13.0 | 13.5 | 14.0 | 14.5 | 15.0 | 15.5 | 16.0 | 16.5 | 17.0 | 17.5 | 18.0 | 18.5 |

 "5L"
$$\rightarrow$$
 VRGL = 3.0V VSUB = 12.0V

- *3 1) Current to each pin when 18V is applied to VDD, VOUT, Vss and SUB pins, while pins that are not tested are grounded.
 - 2) Current to each pin when 20V is applied sequentially to $V\phi_1$, $V\phi_2$, $V\phi_3$ and $V\phi_4$ pins, while pins that are not tested are grounded. However, 20V is applied to SUB pin.
 - 3) Current to each pin when 15V is applied sequentially to RG, LHφ1, Hφ1, Hφ2 and Vgg pins, while pins that are not tested are grounded. However, 15V is applied to SUB pin.
 - 4) Current to V_L pin when 30V is applied to Vφ1, Vφ2, Vφ3, Vφ4, V_{DD} and V_{OUT} pins or when, 24V is applied to RG pin or when, 20V is applied to V_{GG}, Vss, Hφ1, Hφ2 and LHφ1 pins, while V_L pin is grounded. However, GND and SUB pins are left open.

^{*2} VL setting is the VvL voltage of the vertical transfer clock waveform.

^{*4} Current to SUB pin when 55V is applied to SUB pin, while pins that are not tested are grounded.

Clock Voltage Conditions

| Item | Symbol | Min. | Тур. | Max. | Unit | Waveform diagram | Remarks |
|-------------------------|---------------------------|-------|------|-------|------|------------------|--------------------------------------|
| Readout clock voltage | Vvт | 14.55 | 15.0 | 15.45 | V | 1 | |
| | VvH1, VvH2 | -0.05 | 0 | 0.05 | V | 2 | VvH = (VvH1 + VvH2)/2 |
| | VvH3, VvH4 | -0.2 | 0 | 0.05 | V | 2 | |
| | VVL1, VVL2, VVL3, VVL4 | -9.0 | -8.5 | -8.0 | V | 2 | Vvl = (Vvl3 + Vvl4)/2 |
| | Vφv | 7.8 | 8.5 | 9.05 | V | 2 | $V\phi V = VVHN - VVLN (n = 1 to 4)$ |
| Vertical transfer clock | VvH1 — VvH2 | | | 0.1 | V | 2 | |
| voltage | VvH3 – VvH | -0.25 | | 0.1 | V | 2 | |
| | VvH4 — VvH | -0.25 | | 0.1 | V | 2 | |
| | Vvнн | | | 0.5 | V | 2 | High-level coupling |
| | VvHL | | | 0.5 | V | 2 | High-level coupling |
| | VvLH | | | 0.5 | V | 2 | Low-level coupling |
| | VVLL | | | 0.5 | V | 2 | Low-level coupling |
| Horizontal transfer | Vфн, VфLн | 4.75 | 5.0 | 5.25 | V | 3 | *5 |
| clock voltage | VHL, VLHL | -0.05 | 0 | 0.05 | V | 3 | *5 |
| Reset gate clock | Vørg | 4.5 | 5.0 | 5.5 | V | 4 | *6 |
| voltage | VRGLH – VRGLL | | | 0.8 | V | 4 | Low-level coupling |
| Substrate clock voltage | Vфѕив | 22.5 | 23.5 | 24.5 | V | 5 | _ |

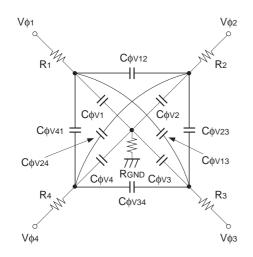
^{*5} The horizontal final stage transfer clock input pin LHφ1 is connected to the horizontal transfer clock input pin Hφ1.

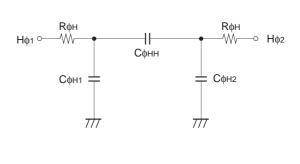
^{*6} The reset gate clock voltage need not be adjusted when reset gate clock is driven when the specifications are as given below. In this case, the reset gate clock voltage setting indicated on the back of the image sensor has not significance.

| Item | Symbol | Min. | Тур. | Max. | Unit | Waveform diagram | Remarks |
|------------------|--------|------|------|------|------|------------------|---------|
| Reset gate clock | VRGL | -0.2 | 0 | 0.2 | V | 4 | |
| voltage | Vþrg | 8.5 | 9.0 | 9.5 | V | 4 | |

Clock Equivalent Circuit Constant

| Item | Symbol | Min. | Тур. | Max. | Unit | Remarks |
|---|----------------|------|------|------|------|---------|
| Capacitance between vertical transfer | Сфу1, Сфу3 | | 1000 | | pF | |
| clock and GND | Сф∨2, Сф∨4 | | 560 | | pF | |
| | СфV12, СфV34 | | 470 | | pF | |
| Capacitance between vertical transfer | Сф∨23, Сф∨41 | | 390 | | pF | |
| clocks | СфV13 | | 180 | | pF | |
| | Сф∨24 | | 100 | | pF | |
| Capacitance between horizontal transfer clock and GND | Сфн1, Сфн2 | | 47 | | pF | |
| Capacitance between horizontal transfer clocks | Сфнн | | 51 | | pF | |
| Capacitance between horizontal final stage transfer clock and GND | Сфін | | 8 | | pF | |
| Capacitance between reset gate clock and GND | Сфяс | | 8 | | pF | |
| Capacitance between substrate clock and GND | Сфѕив | | 270 | | pF | |
| Vertical transfer clock series resistor | R1, R2, R3, R4 | | 80 | | Ω | |
| Vertical transfer clock ground resistor | RGND | | 15 | | Ω | |
| Horizontal transfer clock series resistor | Rфн | | 15 | | Ω | |



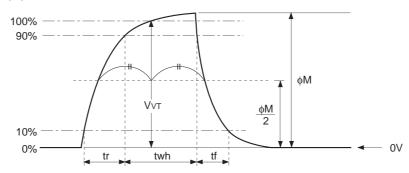


Vertical transfer clock equivalent circuit

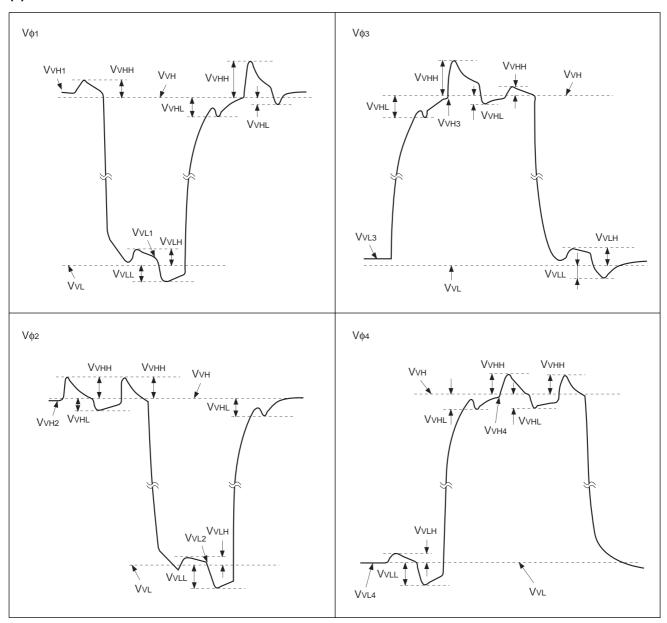
Horizontal transfer clock equivalent circuit

Drive Clock Waveform Conditions

(1) Readout clock waveform



(2) Vertical transfer clock waveform

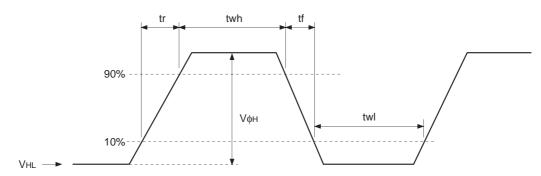


VvH = (VvH1 + VvH2)/2

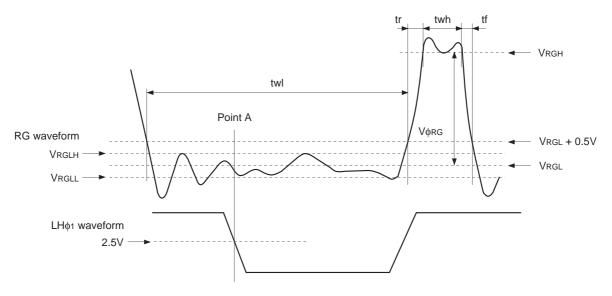
 $V \lor L = (V \lor L3 + V \lor L4)/2$

 $V\phi V = VVHN - VVLN (n = 1 to 4)$

(3) Horizontal transfer clock waveform



(4) Reset gate clock waveform



VRGLH is the maximum value and VRGLL is the minimum value of the coupling waveform during the period from Point A in the above diagram until the rising edge of RG.

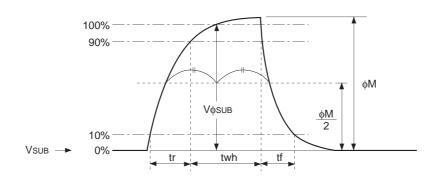
In addition, VRGL is the average value of VRGLH and VRGLL.

$$V_{RGL} = (V_{RGLH} + V_{RGLL})/2$$

Assuming VRGH is the minimum value during the interval twh, then:

$$V\phi RG = VRGH - VRGL$$

(5) Substrate clock waveform



Clock Switching Characteristics

Note) Because the horizontal final stage transfer clock $LH\phi_1$ is connected to the horizontal transfer clock $H\phi_1$, specifications will be the same as $H\phi_1$.

| | Item | Symbol | | twh | | | twl | | | tr | | | tf | | Unit | Remarks | |
|------------------------------|---------------------------|-----------------------|------|------|------|------|------|------|------|------|------|------|------|------|-------|------------------------|--|
| | item | Cymbol | Min. | Тур. | Max. | Min. | Тур. | Max. | Min. | Тур. | Max. | Min. | Тур. | Мах. | Offic | Remarks | |
| Rea | dout clock | VT | 2.3 | 2.5 | | | | | | 0.5 | | | 0.5 | | μs | During readout | |
| Vert cloc | ical transfer k | Vφ1, Vφ2, Vφ3, Vφ4 | | | | | | | | | | 15 | | 250 | ns | *1 | |
| _ <u>~</u> | During imaging | Ηφ1, LΗφ1 | 18 | 24 | | 19.5 | 26 | | | 10 | 17.5 | | 10 | 17.5 | 20 | *2 | |
| r clc | | Нф2 | 21 | 26 | | 19 | 24 | | | 10 | 15 | | 10 | 15 | ns | _ | |
| Horizontal transfer clock | During parallel-serial | Ηφ1, LΗφ1 | | 6.41 | | | | | | 0.01 | | | 0.01 | | | | |
| tra | conversion | Нф2 | | | | | 6.41 | | | 0.01 | | | 0.01 | | μs | | |
| Res | et gate clock | φRG | 11 | 13 | | | 51 | | | 3 | | | 3 | | ns | | |
| Sub | strate clock | фSUB | 1.5 | 1.8 | | | | | | | 0.5 | | | 0.5 | μs | During drain charge | |

^{*1} When vertical transfer clock driver CXD1267AN is used.

^{*2} tf \geq tr - 2ns, and the cross-point voltage (VcR) for the H ϕ 1 · LH ϕ 1 rising side of the H ϕ 1 · LH ϕ 1 and H ϕ 2 waveforms must be at least 2.5V.

| Item | Symbol | | two | Unit | Remarks | |
|---------------------------|-----------------|------|------|------|---------|---------|
| nem | Symbol | Min. | Тур. | Max. | Offic | Remarks |
| Horizontal transfer clock | Ηφ1 - LΗφ1, Ηφ2 | 16 | 20 | | ns | *3 |

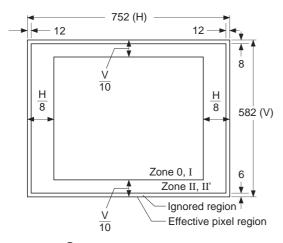
^{*3} The overlap period for twh and twl of horizontal transfer clocks $H\phi_1 \cdot LH\phi_1$ and $H\phi_2$ is two.

Image Sensor Characteristics

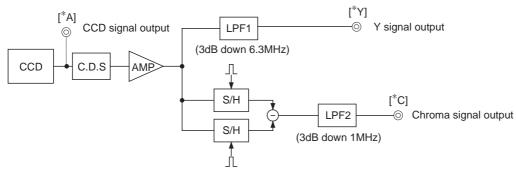
 $(Ta = 25^{\circ}C)$

| Item | Symbol | Min. | Тур. | Max. | Unit | Measurement method | Remarks |
|--------------------------|--------|------|-------|-------|------|--------------------|---------------|
| Sensitivity | S | 360 | 460 | | mV | 1 | |
| Saturation signal | Ysat | 540 | | | mV | 2 | Ta = 60°C |
| Smear | Sm | | 0.002 | 0.007 | % | 3 | |
| Video signal shading | SHy | | | 20 | % | 4 | Zone 0, I |
| Video signal snading | Sily | | | 25 | % | 4 | Zone 0 to II' |
| Uniformity between video | ΔSr | | | 10 | % | 5 | |
| signal channels | ΔSb | | | 10 | % | 5 | |
| Dark signal | Ydt | | | 2 | mV | 6 | Ta = 60°C |
| Dark signal shading | ΔYdt | | | 1 | mV | 7 | Ta = 60°C |
| Flicker Y | Fy | | | 2 | % | 8 | |
| Flicker R-Y | Fcr | | | 5 | % | 8 | |
| Flicker B-Y | Fcb | | | 5 | % | 8 | |
| Line crawl R | Lcr | | | 3 | % | 9 | |
| Line crawl G | Lcg | | | 3 | % | 9 | |
| Line crawl B | Lcb | | | 3 | % | 9 | |
| Line crawl W | Lcw | | | 3 | % | 9 | |
| Lag | Lag | | | 0.5 | % | 10 | |

Zone Definition of Video Signal Shading



Measurement System



Note) Adjust the amplifier gain so that the gain between [*A] and [*Y] and between [*A] and [*C] equal 1.

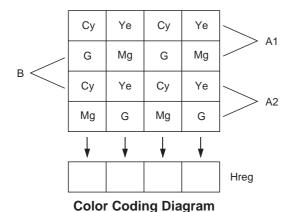
Image Sensor Characteristics Measurement Method

Measurement conditions

 In the following measurements, the substrate voltage and the reset gate clock voltage are set to the values indicated on the device, and the device drive conditions are at the typical values of the bias and clock voltage conditions.

2) In the following measurements, spot blemishes are excluded and, unless otherwise specified, the optical black level (OB) is used as the reference for the signal output, which is taken as the value of Y signal output or chroma signal output of the measurement system.

Color coding of this image sensor & Composition of luminance (Y) and chroma (color difference) signals



As shown in the left figure, fields are read out. The charge is mixed by pairs such as A1 and A2 in the A field. (pairs such as B in the B field)

As a result, the sequence of charges output as signals from the horizontal shift register (Hreg) is, for line A1, (G + Cy), (Mg + Ye), (G + Cy), and (Mg + Ye).

These signals are processed to form the Y signal and chroma (color difference) signal. The Y signal is formed by adding adjacent signals, and the chroma signal is formed by subtracting adjacent signals. In other words, the approximation:

$$Y = \{(G + Cy) + (Mg + Ye)\} \times 1/2$$

= 1/2 {2B + 3G + 2R}

is used for the Y signal, and the approximation:

$$R - Y = \{(Mg + Ye) - (G + Cy)\}\$$

= $\{2R - G\}$

is used for the chroma (color difference) signal. For line A2, the signals output from Hreg in sequence are

$$(Mg + Cy), (G + Ye), (Mg + Cy), (G + Ye).$$

The Y signal is formed from these signals as follows:

$$Y = \{(G + Ye) + (Mg + Cy)\} \times 1/2$$

= 1/2 {2B + 3G + 2R}

This is balanced since it is formed in the same way as for line A1.

In a like manner, the chroma (color difference) signal is approximated as follows:

$$-(B-Y) = \{(G + Ye) - (Mg + Cy)\}\$$

= $-\{2B-G\}$

In other words, the chroma signal can be retrieved according to the sequence of lines from R - Y and - (B - Y) in alternation. This is also true for the B field.

Definition of standard imaging conditions

1) Standard imaging condition I:

Use a pattern box (luminance 706cd/m², color temperature of 3200K halogen source) as a subject. (Pattern for evaluation is not applicable.) Use a testing standard lens with CM500S (t = 1.0mm) as an IR cut filter and image at F5.6. The luminous intensity to the sensor receiving surface at this point is defined as the standard sensitivity testing luminous intensity.

2) Standard imaging condition II:

Image a light source (color temperature of 3200K) with a uniformity of brightness within 2% at all angles. Use a testing standard lens with CM500S (t = 1.0mm) as an IR cut filter. The luminous intensity is adjusted to the value indicated in each testing item by the lens diaphragm.

1. Sensitivity

Set to standard imaging condition I. After selecting the electronic shutter mode with a shutter speed of 1/250s, measure the Y signal (Ys) at the center of the screen and substitute the value into the following formula.

$$S = Ys \times \frac{250}{50} [mV]$$

2. Saturation signal

Set to standard imaging condition II. After adjusting the luminous intensity to 10 times the intensity with average value of the Y signal output, 200mV, measure the minimum value of the Y signal.

3. Smear

Set to standard imaging condition II. With the lens diaphragm at F5.6 to F8, adjust the luminous intensity to 500 times the intensity with average value of the Y signal output, 200mV. When the readout clock is stopped and the charge drain is executed by the electronic shutter at the respective H blankings, measure the maximum value YSm [mV] of the Y signal output and substitute the value into the following formula.

$$Sm = \frac{YSm}{200} \times \frac{1}{500} \times \frac{1}{10} \times 100 \text{ [\%] (1/10V method conversion value)}$$

4. Video signal shading

Set to standard imaging condition II. With the lens diaphragm at F5.6 to F8, adjust the luminous intensity so that the average value of the Y signal output is 200mV. Then measure the maximum (Ymax [mV]) and minimum (Ymin [mV]) values of the Y signal and substitute the values into the following formula.

SHy =
$$(Ymax - Ymin)/200 \times 100$$
 [%]

5. Uniformity between video signal channels

Set to standard imaging condition II. Adjust the luminous intensity so that the average value of the Y signal output is 200mV, and then measure the maximum (Crmax, Cbmax [mV]) and minimum (Crmin, Cbmin [mV]) values of the R - Y and B - Y channels of the chroma signal and substitute the values into the following formula.

$$\Delta Sr = | (Crmax - Crmin)/200 | \times 100 [\%]$$

 $\Delta Sb = | (Cbmax - Cbmin)/200 | \times 100 [\%]$

6. Dark signal

Measure the average value of the Y signal output (Ydt [mV]) with the device ambient temperature 60°C and the device in the light-obstructed state, using the horizontal idle transfer level as a reference.

7. Dark signal shading

After measuring 6, measure the maximum (Ydmax [mV]) and minimum (Ydmin [mV]) values of the Y signal output and substitute the values into the following formula.

$$\Delta Ydt = Ydmax - Ydmin [mV]$$

8. Flicker

1) Fy

Set to standard imaging condition II. Adjust the luminous intensity so that the average value of the Y signal output is 200mV, and then measure the difference in the signal level between fields (Δ Yf [mV]). Then substitute the value into the following formula.

$$Fy = (\Delta Yf/200) \times 100 [\%]$$

2) Fcr, Fcb

Set to standard imaging condition II. Adjust the luminous intensity so that the average value of the Y signal output is 200mV, insert an R or B filter, and then measure both the difference in the signal level between fields of the chroma signal (Δ Cr, Δ Cb) as well as the average value of the chroma signal output (CAr, CAb). Substitute the values into the following formula.

Fci =
$$(\Delta \text{Ci/CAi}) \times 100 \text{ [\%]}$$
 (i = r, b)

9. Line crawls

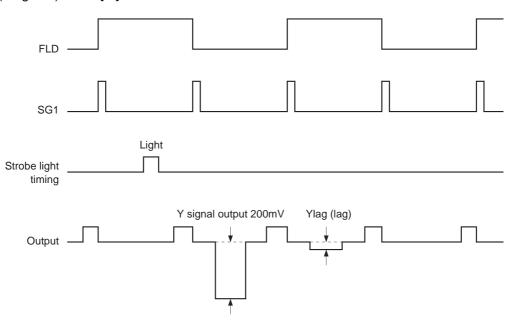
Set to standard imaging condition II. Adjust the luminous intensity so that the average value of the Y signal output is 200mV, and then insert a white subject and R, G, and B filters and measure the difference between Y signal lines for the same field (Δ Ylw, Δ Ylr, Δ Ylg, Δ Ylb [mV]). Substitute the values into the following formula.

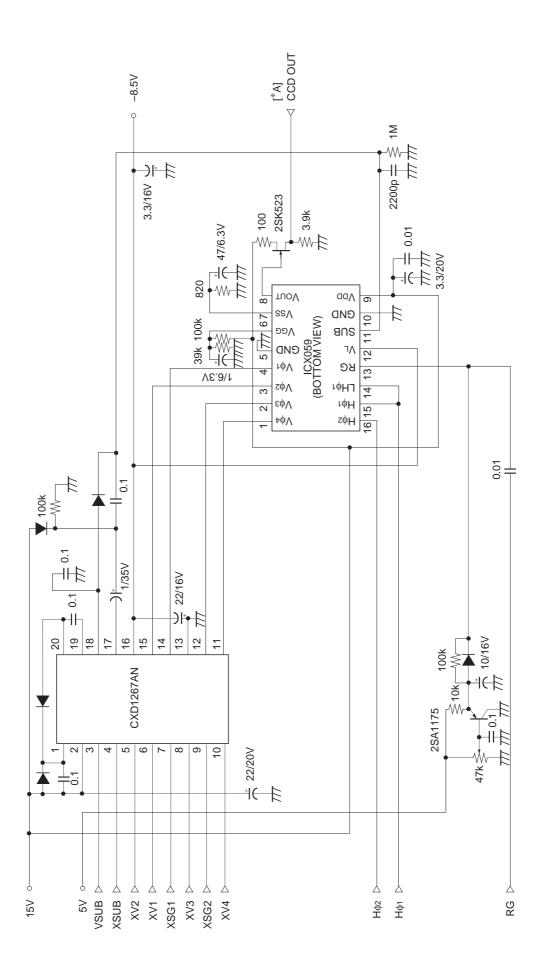
Lci =
$$(\Delta Y li/200) \times 100 [\%]$$
 (i = w, r, g, b)

10. Lag

Adjust the Y signal output value generated by strobe light to 200mV. After setting the strobe light so that it strobes with the following timing, measure the residual signal (Ylag). Substitute the value into the following formula.

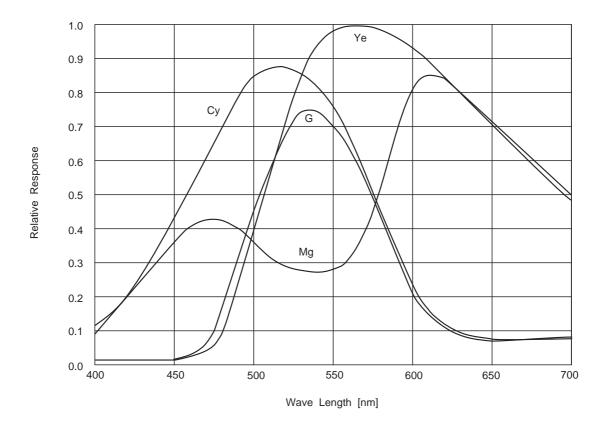
$$Lag = (Ylag/200) \times 100 [\%]$$



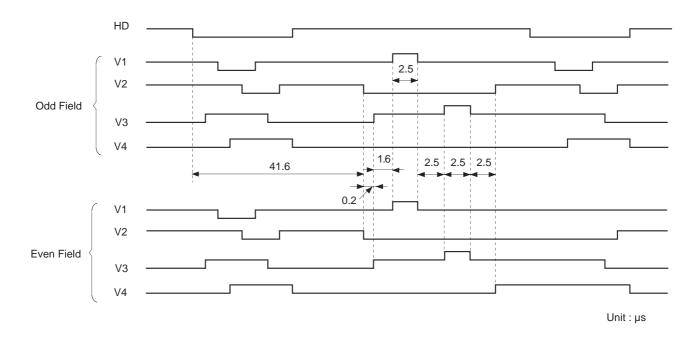


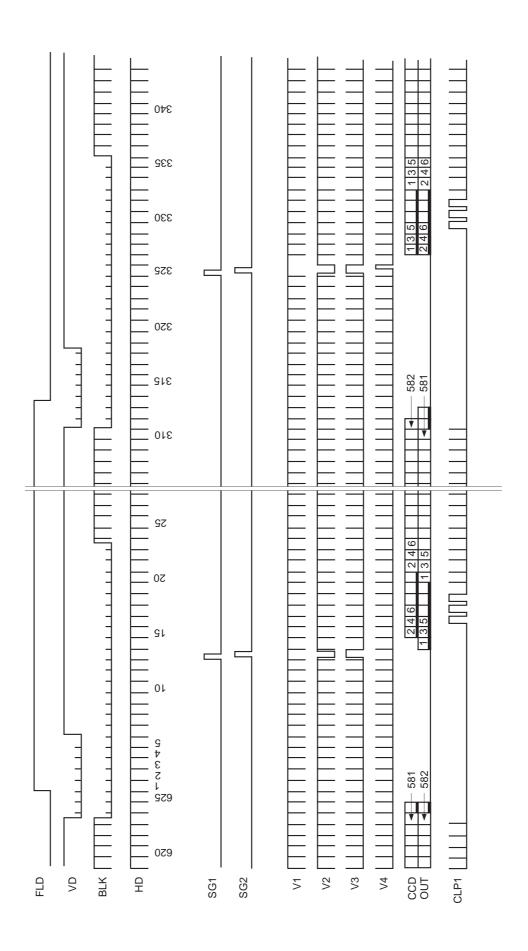
Spectral Sensitivity Characteristics

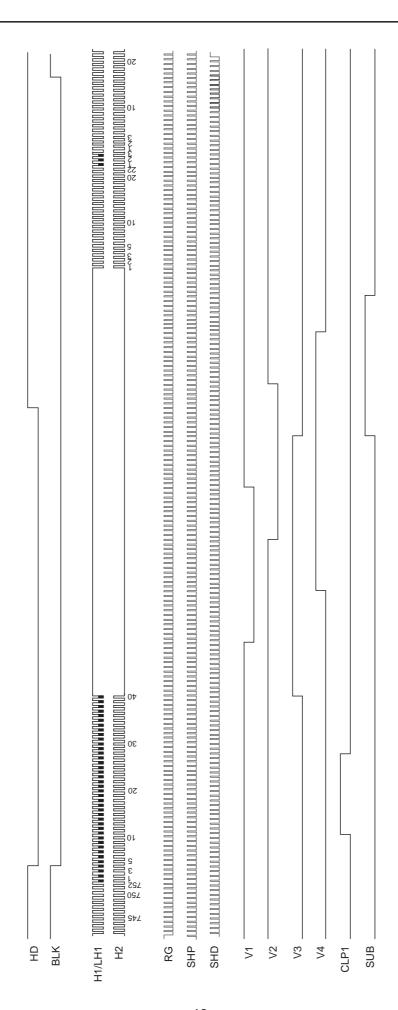
(Includes lens characteristics, excludes light source characteristics)



Sensor Readout Clock Timing Chart







Notes on Handling

1) Static charge prevention

CCD image sensors are easily damaged by static discharge. Before handling be sure to take the following protective measures.

- a) Either handle bare handed or use non-chargeable gloves, clothes or material. Also use conductive shoes.
- b) When handling directly use an earth band.
- c) Install a conductive mat on the floor or working table to prevent the generation of static electricity.
- d) Ionized air is recommended for discharge when handling CCD image sensor.
- e) For the shipment of mounted substrates, use boxes treated for the prevention of static charges.

2) Soldering

- a) Make sure the package temperature does not exceed 80°C.
- b) Solder dipping in a mounting furnace causes damage to the glass and other defects. Use a ground 30W soldering iron and solder each pin in less than 2 seconds. For repairs and remount, cool sufficiently.
- c) To dismount an image sensor, do not use a solder suction equipment. When using an electric desoldering tool, use a thermal controller of the zero cross On/Off type and connect it to ground.

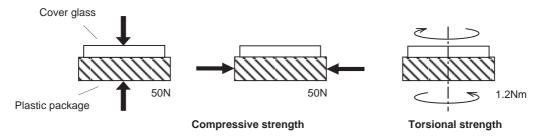
3) Dust and dirt protection

Image sensors are packed and delivered by taking care of protecting its glass plates from harmful dust and dirt. Clean glass plates with the following operation as required, and use them.

- a) Perform all assembly operations in a clean room (class 1000 or less).
- b) Do not either touch glass plates by hand or have any object come in contact with glass surfaces. Should dirt stick to a glass surface, blow it off with an air blower. (For dirt stuck through static electricity ionized air is recommended.)
- c) Clean with a cotton bud and ethyl alcohol if the grease stained. Be careful not to scratch the glass.
- d) Keep in a case to protect from dust and dirt. To prevent dew condensation, preheat or precool when moving to a room with great temperature differences.
- e) When a protective tape is applied before shipping, just before use remove the tape applied for electrostatic protection. Do not reuse the tape.

4) Installing (attaching)

a) Remain within the following limits when applying a static load to the package. Do not apply any load more than 0.7mm inside the outer perimeter of the glass portion, and do not apply any load or impact to limited portions. (This may cause cracks in the package.)



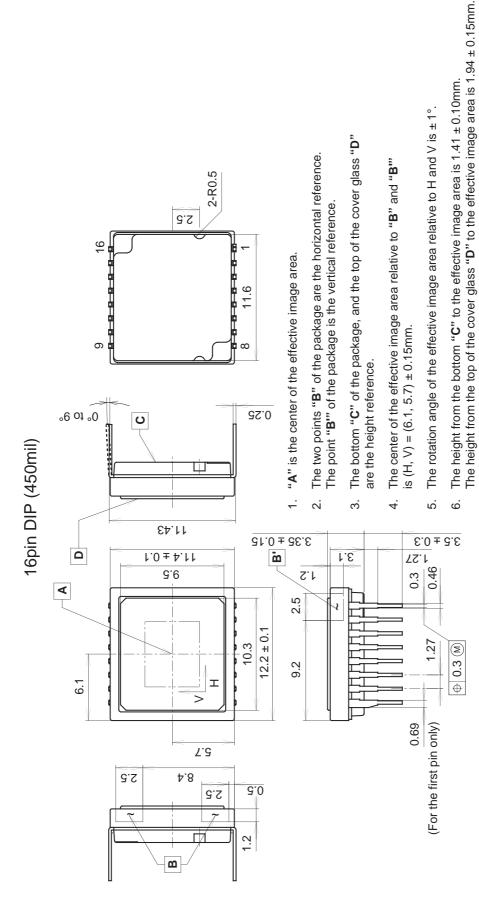
b) If a load is applied to the entire surface by a hard component, bending stress may be generated and the package may fracture, etc., depending on the flatness of the bottom of the package. Therefore, for installation, use either an elastic load, such as a spring plate, or an adhesive.

- c) The adhesive may cause the marking on the rear surface to disappear, especially in case the regulated voltage value is indicated on the rear surface. Therefore, the adhesive should not be applied to this area, and indicated values should be transferred to the other locations as a precaution.
- d) The notch of the package is used for directional index, and that can not be used for reference of fixing. In addition, the cover glass and seal resin may overlap with the notch of the package.
- e) If the lead bend repeatedly and the metal, etc., clash or rub against the package, the dust may be generated by the fragments of resin.
- f) Acrylate anaerobic adhesives are generally used to attach CCD image sensors. In addition, cyanoacrylate instantaneous adhesives are sometimes used jointly with acrylate anaerobic adhesives. (reference)

5) Others

- a) Do not expose to strong light (sun rays) for long periods, color filters will be discolored. When high luminance objects are imaged with the exposure level control by electronic-iris, the luminance of the image-plane may become excessive and discolor of the color filter will possibly be accelerated. In such a case, it is advisable that taking-lens with the automatic-iris and closing of the shutter during the power-off mode should be properly arranged. For continuous using under cruel condition exceeding the normal using condition, consult our company.
- b) Exposure to high temperature or humidity will affect the characteristics. Accordingly avoid storage or usage in such conditions.
- c) The brown stain may be seen on the bottom or side of the package. But this does not affect the CCD characteristics.

Unit: mm Package Outline



PACKAGE STRUCTURE

7

| PACKAGE MATERIAL LEAD TREATMENT LEAD MATERIAL PACKAGE WEIGHT | Plastic | GOLD PLATING | 42 ALLOY | 0.9g |
|--|------------------|----------------|---------------|----------------|
| | PACKAGE MATERIAL | LEAD TREATMENT | LEAD MATERIAL | PACKAGE WEIGHT |

| The tilt of the effective image area relative to the bottom "C" is less than 50µm. | The tilt of the effective image area relative to the top "D" of the cover glass is less than 50µm. | The thickness of the cover glass is 0.75mm, and the refractive index is 1.5. |
|--|--|--|
| of the effective image area relative t | of the effective image area relative to | kness of the cover glass is 0.75mm, |
| The tilt | The tilt | The thic |

The notches on the bottom of the package are used only for directional index, they must

not be used for reference of fixing.

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